Plans for test beam at LP1 - Bonn University

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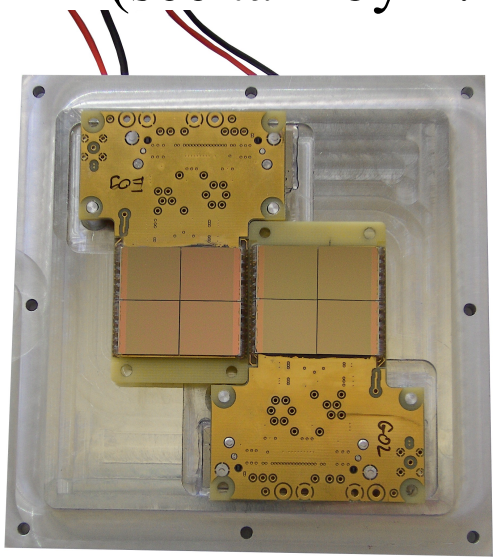
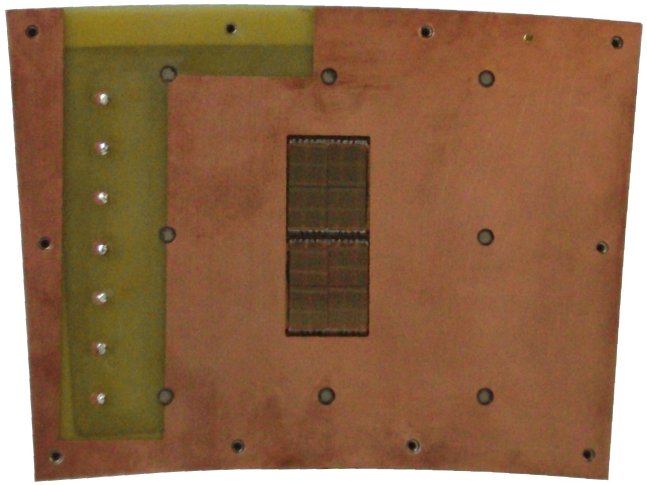
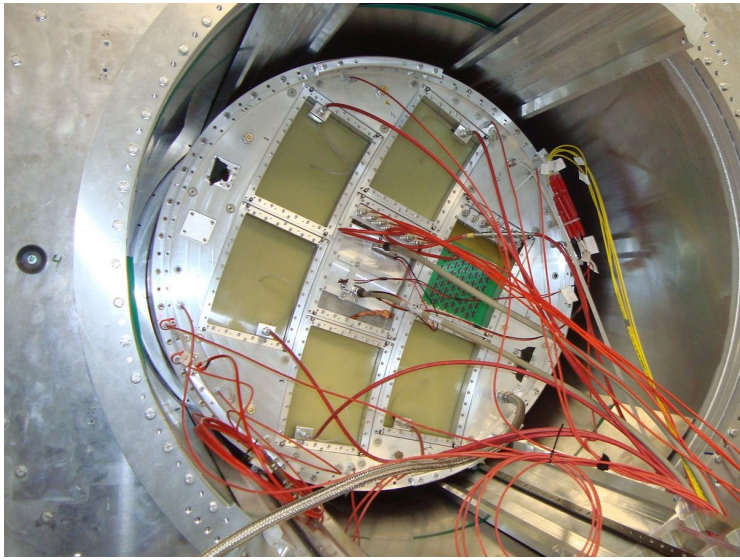
'Short term' plans (early 2010)

Repair GEM & Timepix module with 2 Quadboards
(see talk by F. Klöckner)





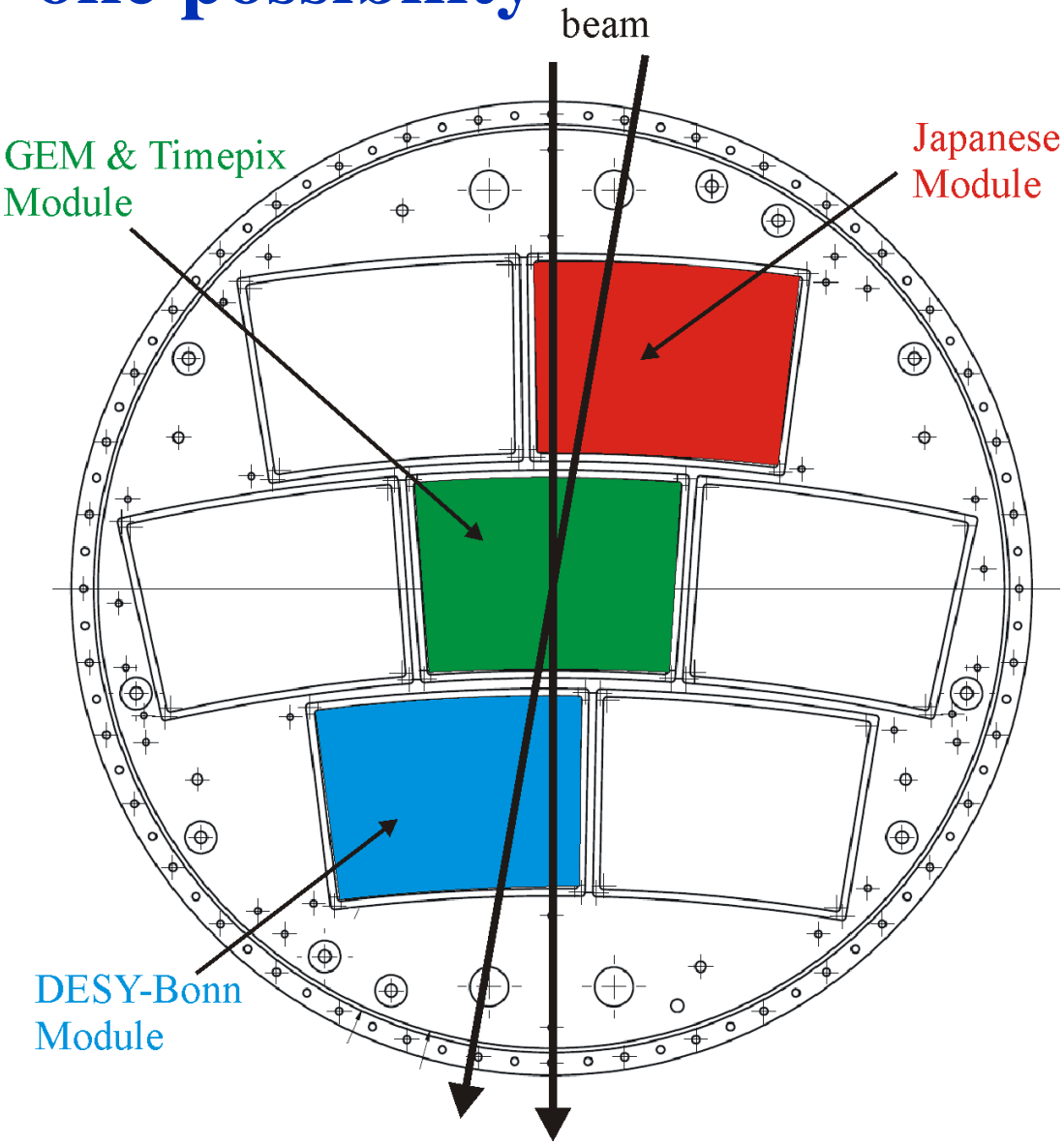


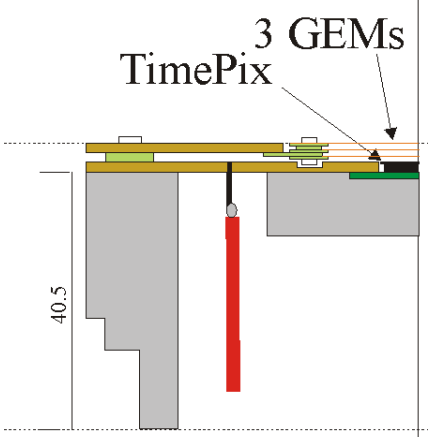
Data taking with different modules and Silicon trackers at the same time.

e.g. 3 GEM & Timepix Module
Japanese Module
DESY-Bonn Module

=> requirement of el. potentials have to be compatible

Data taking with different modules one possibility

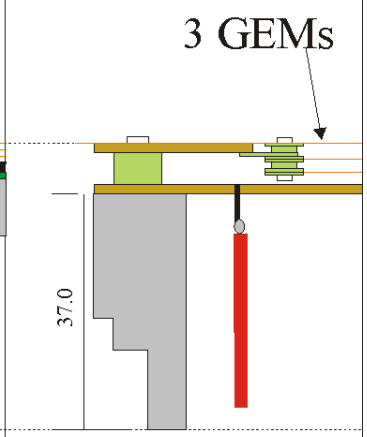




3 GEMs + TimePix

voltages:

GEM1:	260 V
E_{trans1}:	250 V
GEM2:	260 V
E_{trans2}:	250 V
GEM3:	260 V
E_{ind}:	350 V
V_{tot}:	1630 V



3 GEMs + Pads ($1.1 * 5.6$ mm²)

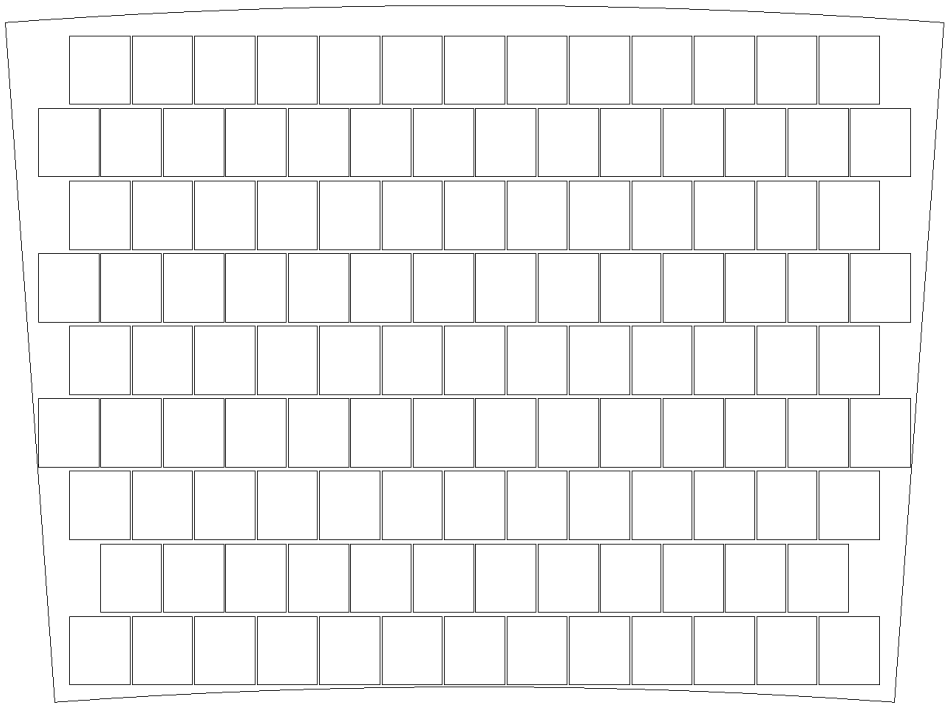
voltages:

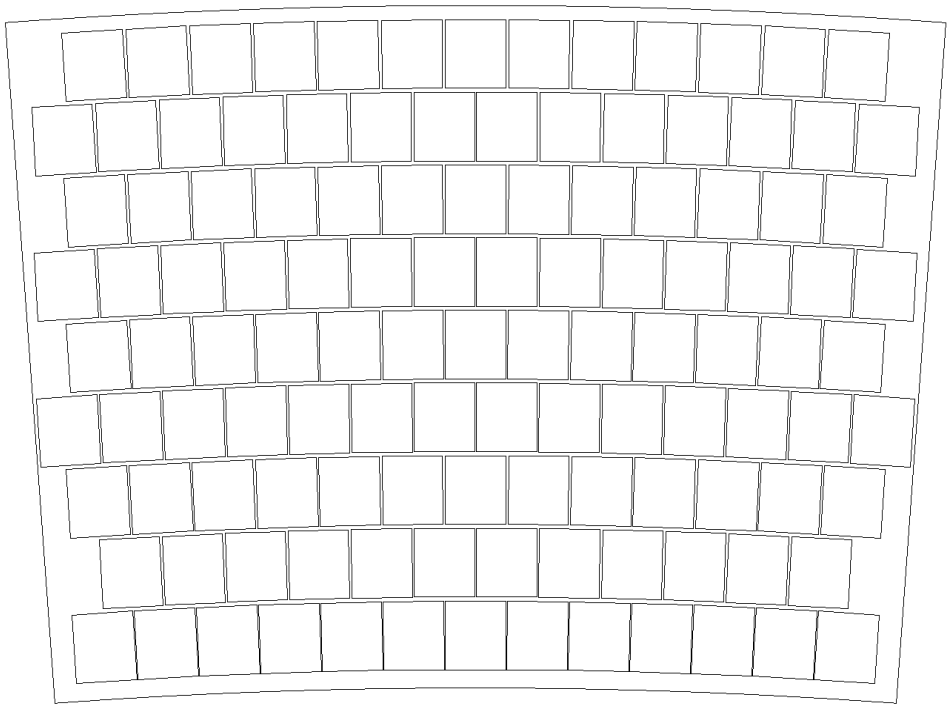
GEM1:	230 V
E_{trans1}:	280 V
GEM2:	230 V
E_{trans2}:	280 V
GEM3:	230 V
E_{ind}:	380 V
V_{tot}:	1630 V

'Long-term' plans (end 2010)

LP1 module covered completely with Timepix modules

First ideas: 119 Timepix chips (more than 1 wafer, $\approx 7.8 \cdot 10^6$ channels)





<u>Gas amplification:</u> triple GEM, possibly also InGrids

<u>Readout electronics:</u> 'Scalable Readout System' developed at CERN in the framework of RD-51